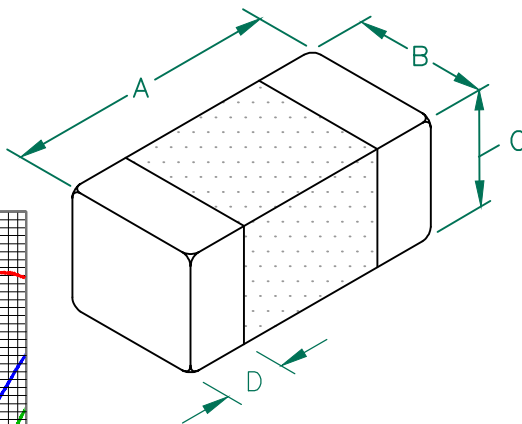
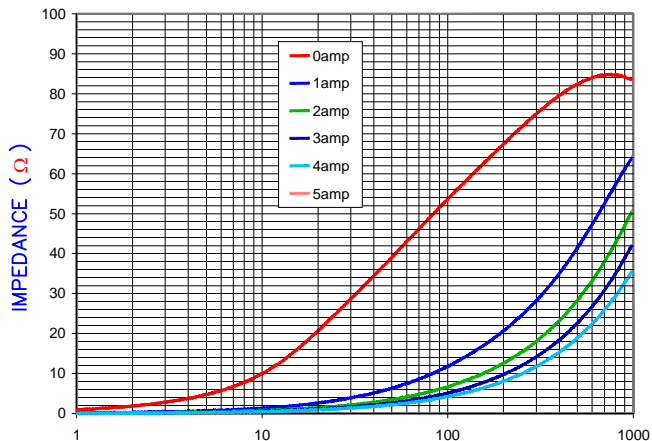


HI0603P600R-10

PHYSICAL DIMENSIONS:

A	1.60 [.063]	+ 0.15	[-.006]
B	0.80 [.031]	+ 0.15	[-.006]
C	0.80 [.031]	+ 0.15	[-.006]
D	0.36 [.014]	+ 0.15	[-.006]

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



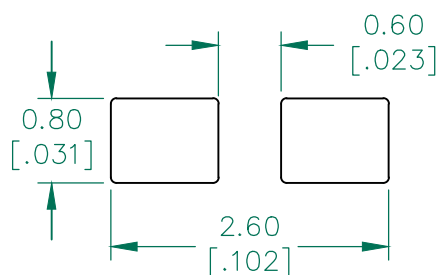
ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	60		
Minimum	45		
Maximum	75	0.030	4000 mA

NOTES: UNLESS OTHERWISE SPECIFIED

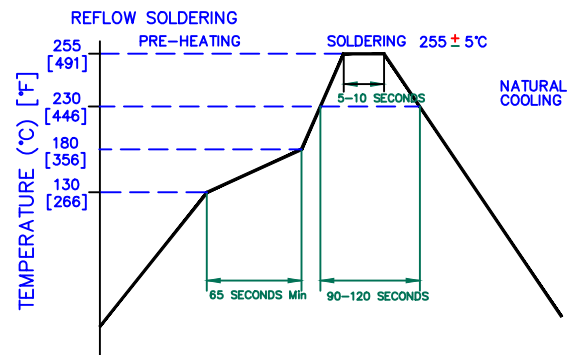
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING

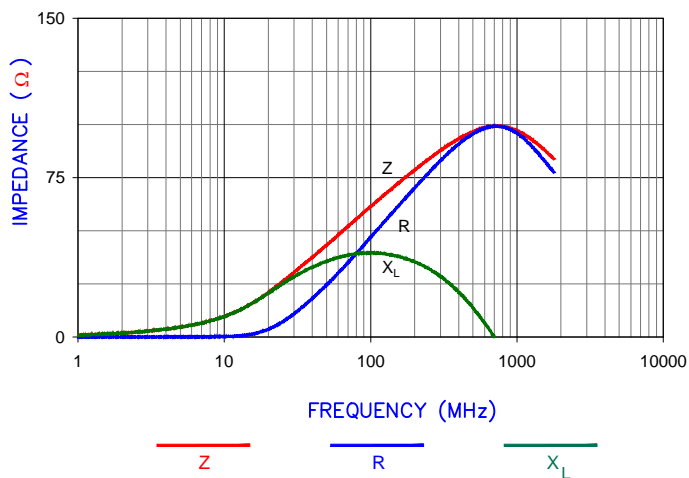


(For wave soldering, add 0.762 [.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS



|Z| , R, AND X vs. FREQUENCY



AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3185



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.	
D	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER:	REV
C	UPDATE COMPANY LOGO	05/29/09	JRK	HI0603P600R-10	D
B	UPDATE COMPANY LOGO ADD ROHS SYMBOL	01/16/08	JRK	DATE:	04/02/04
A	ORIGINAL DRAFT	04/02/04	TMB	SCALE:	-
REV	DESCRIPTION	DATE	INT	GAD #	HI0603P600R-10-D
				TOOL #	-
				SHEET:	1 of 1

